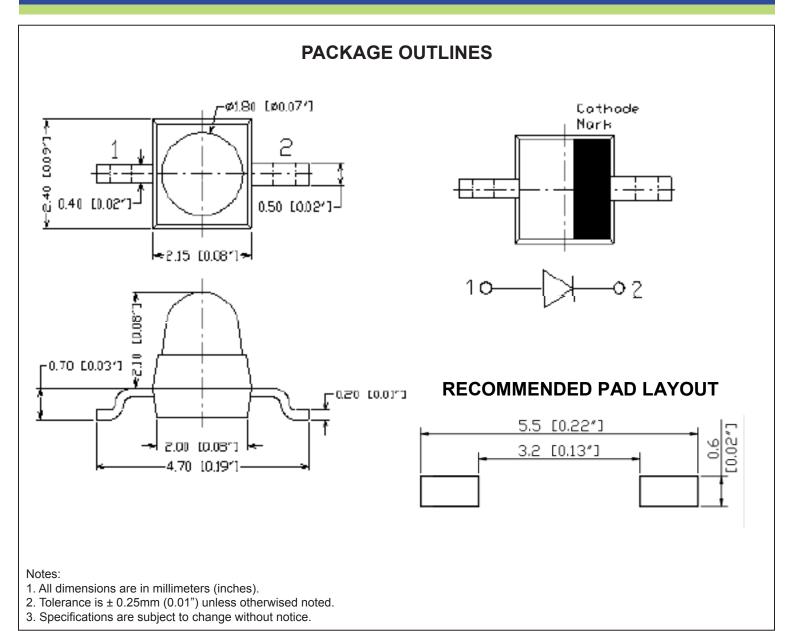


SPECIFICATION CSM28G2CG



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSM28G2CG	InGaAIP	Green	Water Clear	20°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	160	520	-	mcd
Forward Voltage	VF	IF = 20mA	-	2.0	2.5	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 10mA	-	20	-	Deg
Peak Wavelength	λ P	IF = 20mA	-	572	-	nm
Dominant Wavelength	λ D	IF = 20mA	565	570	575	nm

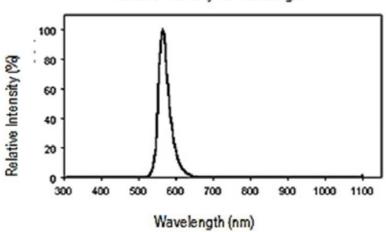
^{*}Tolerance of viewing angle: -10 / +5 deg.



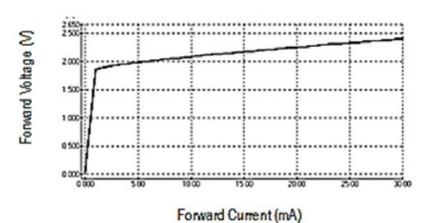


OPTICAL CHARACTERISTIC CURVES

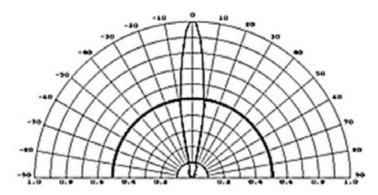
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

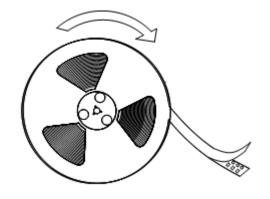




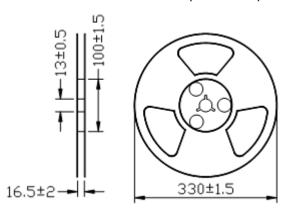


PACKAGING SPECIFICATION

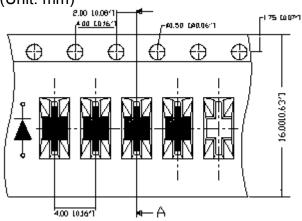
Feeding Direction

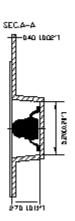


Dimensions of Reel (Unit: mm)

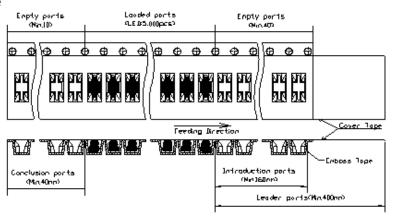


Dimensions of Tape (Unit: mm)





Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamp is two;
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000 pcs/Reel

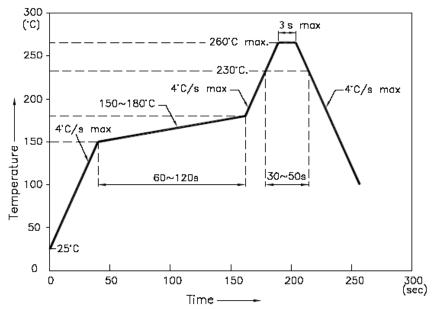




SOLDERING CONDITIONS

REFLOW PROFILE

Reflow Temp/Time



Notes:

- 1. We recommend the reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.

Soldering Iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter ($\pm 10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.